

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

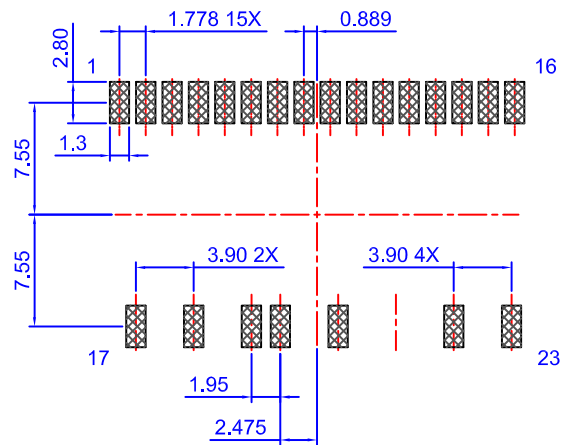
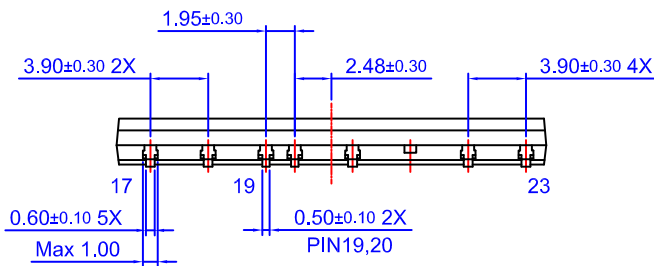
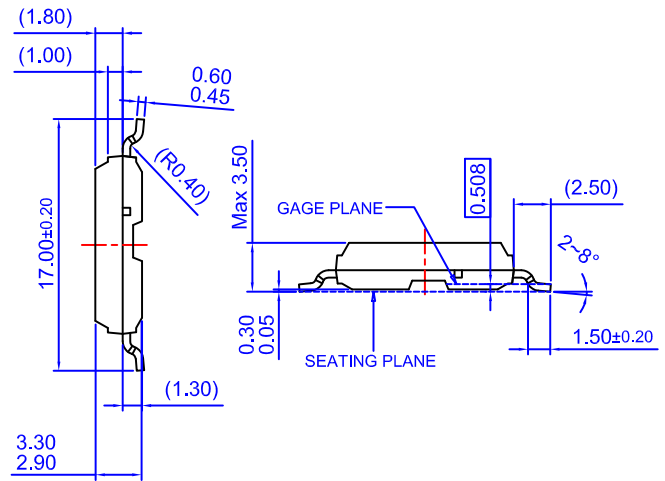
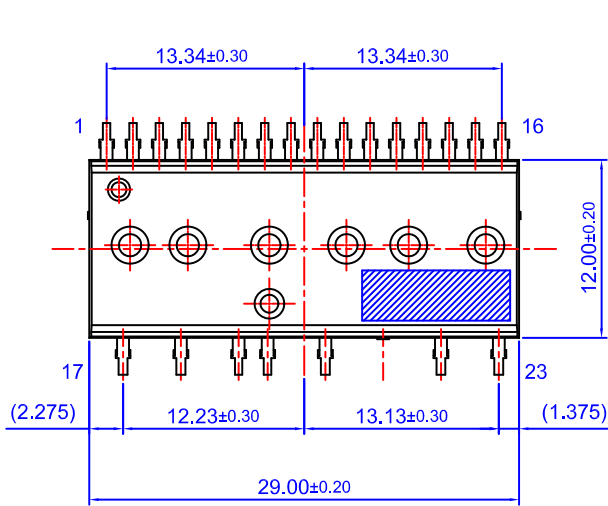
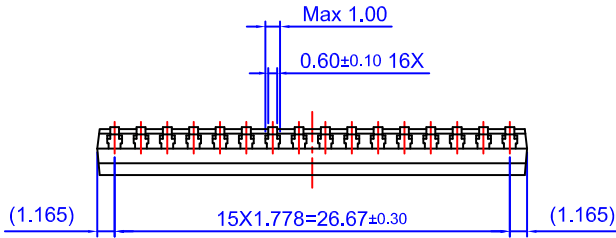
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SPM5H-023 / 23LD, PDD STD, SPM23-BD (Ver1.5) SMD TYPE

CASE MODEM
ISSUE O

DATE 31 JAN 2017



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE

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